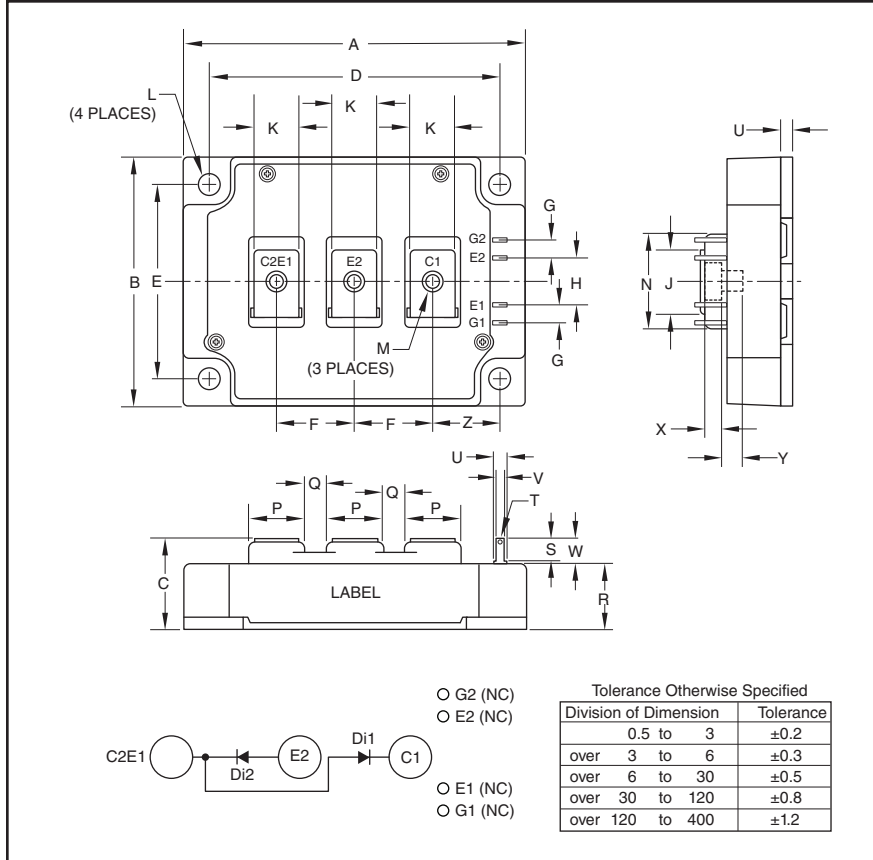


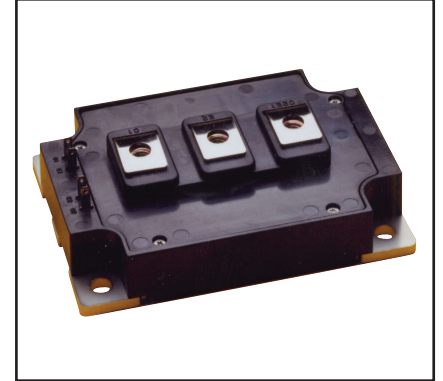
### Super Fast Recovery Dual Diode Module 400 Amperes/1200 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.15	80.0
C	1.14+0.04/-0.02	29.0+1.0/-0.5
D	3.66±0.01	93.0±0.25
E	2.44±0.01	62.0±0.25
F	0.98	25.0
G	0.24	6.0
H	0.59	15.0
J	0.81	20.5
K	0.55	14.0
L	0.26 Dia.	Dia. 6.5
M	M6 Metric	M6

Dimensions	Inches	Millimeters
N	1.18	30.0
P	0.71	18.0
Q	0.28	7.0
R	0.83	21.2
S	0.30	7.5
T	0.02	0.5
U	0.16	4.0
V	0.11	2.8
W	0.33	8.5
X	0.21	5.3
Y	0.47	12.0
Z	0.85	21.5



#### Description:

Powerex Super Fast Recovery Dual Diode modules are designed for use in applications requiring fast switching. The modules are isolated for easy mounting with other components on common heatsinks.

#### Features:

- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Copper Baseplate for Easy Heat Sinking
- RoHS Compliant

#### Applications:

- AC Motor Control
- Motion/Servo Control
- UPS
- Welding Power Supplies
- Laser Power Supplies

#### Ordering Information:

Example: Select the complete module number you desire from the table - i.e. RM400DY-24S is a 1200V ( $V_{CES}$ ), 400 Ampere Super Fast Recovery Dual Diode Power Module.

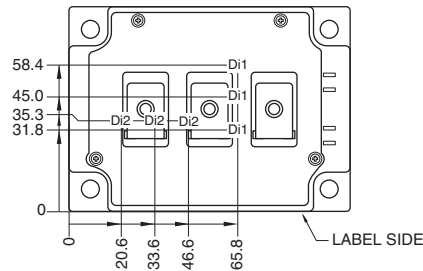
Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
RM	400	24

**RM400DY-24S**  
**Super Fast Recovery Dual Diode Module**  
 400 Amperes/1200 Volts

**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Rating	Units
Repetitive Peak Reverse Voltage	$V_{RRM}$	1200	Volts
Non-repetitive Peak Reverse Voltage	$V_{RSM}$	1200	Volts
Reverse DC Blocking Voltage	$V_{R(DC)}$	960	Volts
DC Forward Current (DC, $T_C = 68^\circ\text{C}$ )*1,2	$I_{DC}$	400	Amperes
Surge Non-repetitive Forward Current (1 Cycle of Half Wave at 60Hz, Peak Value, $T_j = 25^\circ\text{C}$ Start, $V_{RM} = 0\text{V}$ )	$I_{FSM}$	2000	Amperes
Current Square Time for Fusing ( $t_w = 8.3\text{ms}$ , $T_j = 25^\circ\text{C}$ Start, Value for One Cycle of Surge Current)	$I^2t$	$1.66 \times 10^4$	$\text{A}^2\text{s}$
Isolation Voltage (Terminals to Baseplate, RMS, $f = 60\text{Hz}$ , AC 1 minute)	$V_{ISO}$	2500	Volts
Junction Temperature*1	$T_j$	-40 ~ +150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 ~ +125	$^\circ\text{C}$

\*1 Junction temperature ( $T_j$ ) should not increase beyond  $T_{j(max)}$  rating.  
 \*2 Case temperature ( $T_C$ ) and heatsink temperature ( $T_s$ ) is measured on the surface (mounting side) of the baseplate and the heatsink side just under the chips. Refer to the figure to the right for chip location. The heatsink thermal resistance should be measured just under the chips.



Di1 / Di2: FWDi  
 Each mark points to the center position of each chip.

**RM400DY-24S**  
**Super Fast Recovery Dual Diode Module**  
 400 Amperes/1200 Volts

**Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Reverse Current	$I_{RRM}$	$V_R = V_{RRM}, T_j = 125^\circ\text{C}$	—	—	10	mA
Forward Voltage	$V_F$	$I_F = 400\text{A}, T_j = 25^\circ\text{C}^{*3}$	—	2.6	3.3	Volts
Reverse Recovery Time	$t_{rr}$	$V_{RM} = 600\text{V}, I_F = 400\text{A},$	—	—	250	ns
Reverse Recovery Charge	$Q_{rr}$	$di/dt = 3500\text{ A}/\mu\text{s}, \text{ Inductive Load}$	—	19	—	$\mu\text{C}$
Reverse Recovery Energy per Pulse	$E_{rr}$	$T_j = 125^\circ\text{C}, \text{ Inductive Load}$	—	34	—	mJ
Internal Lead Resistance	$R_{AA'} + KK'$	Main Terminals-Chip, Per Diode, $T_C = 25^\circ\text{C}$	—	0.75	—	m $\Omega$

**Thermal Resistance Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Thermal Resistance, Junction to Case <sup>*2</sup>	$R_{th(j-c)D}$	Per Diode	—	—	0.062	K/W
Contact Thermal Resistance, Case to Heatsink <sup>*2</sup>	$R_{th(c-s)}$	Thermal Grease Applied <sup>*4</sup> (Per 1/2 Module)	—	0.018	—	K/W

**Mechanical Characteristics**

Mounting Torque	$M_t$	Main Terminals, M6 Screw	31	35	40	in-lb
	$M_s$	Mounting to Heatsink, M6 Screw	31	35	40	in-lb
Weight	m		—	580	—	Grams
Flatness of Baseplate	$e_c$	On Centerline X, Y <sup>*5</sup>	-100	—	+100	$\mu\text{m}$

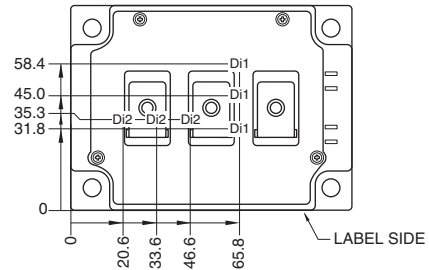
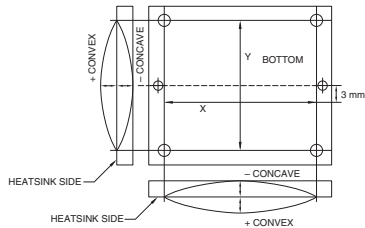
\*2 Case temperature ( $T_C$ ) and heatsink temperature ( $T_s$ ) is measured on the surface (mounting side) of the baseplate and the heatsink side just under the chips. Refer to the figure to the right for chip location.

The heatsink thermal resistance should be measured just under the chips.

\*3 Pulse width and repetition rate should be such as to cause negligible temperature rise.

\*4 Typical value is measured by using thermally conductive grease of  $\lambda = 0.9\text{ [W/(m}\cdot\text{K)]}$ .

\*5 Baseplate (mounting side) flatness measurement points (X, Y) are shown in the figure below.



Di1 / Di2: FWDi  
 Each mark points to the center position of each chip.



**RM400DY-24S**  
**Super Fast Recovery Dual Diode Module**  
 400 Amperes/1200 Volts

